



## EVENTS

### C3NiT Center Day 10 Nov 2022

More than 80 C3NiT members, affiliates and visitors met and discussed C3NiT research at C3NiT day 2022. The program featured 24 presentations, including 3 invited talks (Enrico Zanoni, Michał Boćkowski and Joana Mendes), 2 industrial, 5 project, 14 PhD and PostDoc presentations.

## GRADUATIONS

**Hengfang Zhang:** "Hot-wall MOCVD of N-polar group-III nitride materials and high electron mobility transistor structures", **PhD thesis**

**Alexis Papamichail:** "P-type and polarization doping of GaN in hot-wall MOCVD", **Licentiate thesis**

**Rosalía Delgado Carrascon:** "Epitaxial strategies for defect reduction in GaN for vertical power devices", **Licentiate thesis**

**Björn Hult:** "Design, Fabrication and Characterization of GaN HEMTs for Power Switching Applications", **Licentiate thesis**

**Albert Malmros:** "Investigation on the Optimization of GaN Etching for FinFET Applications", **Master thesis**

**Shiqi Guo:** "AlGaIn/GaN HEMTs for high-frequency applications", **Master thesis**

## PUBLICATIONS

D.-Y. Chen et al. "Impact of the Channel Thickness on Electron Confinement in MOCVD-Grown High Breakdown Buffer-free AlGaIn/GaN Heterostructures", Phys. Status Solidi A 2200496 (2022) [link](#)

B. Hult et al., "High Voltage and Low Leakage GaN-on-SiC MISHEMTs on a "Buffer-Free" Heterostructure", IEEE Electron Dev. Lett. **43**, 781 (2022)

## *C3NiT CONTINUATION !*

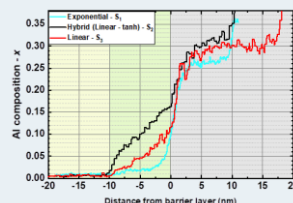
VINNOVA has granted funding for another 5 years of C3NiT! The extension was approved after C3NiT successfully passed the 5-year evaluation and was ranked 2<sup>nd</sup> among all eight Vinnova competence centers. We are looking forward to another successful 5 years!

## PROJECT UPDATES



### Epitaxial growth development

Compositional grading of the channel in AlGaIn/GaN high electron mobility transistors (HEMTs) has been developed. The DC performance reveal improved linearity characteristics making our approach highly promising for low-noise RF amplifiers.



### Vertical GaN power devices

Quasi-vertical GaN FinFETs were fabricated on SiC substrates. The devices demonstrate good electrostatic control of the channel and low on-resistance (below 0.05 mΩcm<sup>2</sup>). The breakdown voltage of 60 V was obtained. Post gate metallization annealing resulted in reduced threshold voltage, on-resistance, and gate leakage.



### HEMT technology

We have demonstrated HEMT devices with 70 nm gate length based on buffer-free epistuctures (QuanFINE) without any degradation in structural quality and 2DEG properties. Devices exhibit excellent electrical characteristics such as high breakdown field of 0.95 MV cm<sup>-1</sup> and DIBL of 20 mV/V at V<sub>DS</sub> of 25 V. ([link](#))



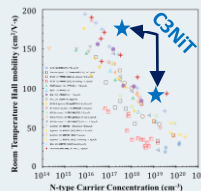
### GaN MMIC

A new batch based on the developed multilayer backend process has recently been finalized. A new feature is an integrated antenna. The circuits await characterization.



### Developing the next generation high-power β-Ga<sub>2</sub>O<sub>3</sub> material

Successful homoepitaxy of β-Ga<sub>2</sub>O<sub>3</sub> (010), with record smooth surface: RMS of 0.8 nm over 10 μm × 10 μm. These epilayers exhibit electron mobility parameters among the best values in the literature μ<sub>a,c</sub> = 170 cm<sup>2</sup>/(Vs) and μ<sub>b</sub> = 12 cm<sup>2</sup>/(Vs) for N = 5 × 10<sup>17</sup> cm<sup>-3</sup>.





## PUBLICATIONS

D.-Y. Chen et al., "Impact of *in situ* NH<sub>3</sub> pre-treatment of LPCVD SiN passivation on GaN HEMT performance", *Semicond. Sci. Technol.* **37**, 035011 (2022)

R. Delgado-Carrascon et al., "Hot-wall MOCVD for high quality GaN homoepitaxy: Understanding nucleation and design of growth strategies", *Cryst. Growth Des.* **22**, 7021 (2022)

P. Kühne et al., "Enhancement of 2DEG effective mass in AlN/Al<sub>0.78</sub>Ga<sub>0.22</sub>N high electron mobility transistor structure determined by THz optical Hall effect", *Appl. Phys. Lett.* **120**, 253102 (2022) [link](#)

D. Gogova et al., "Epitaxial growth of β-Ga<sub>2</sub>O<sub>3</sub> by hot-wall MOCVD", *AIP Advances* **12** 055022 (2022) [link](#)

H. Zhang et al., "On the polarity determination and polarity inversion in nitrogen-polar group III-nitride layers grown on SiC", *J. Appl. Phys.* **131**, 055701 (2022)

A. R. Persson, "Mg segregation at inclined facets of pyramidal inversion domains in GaN:Mg", *Sci. Reports* **12**, 17987 (2022)

D. Q. Tran et al., "Thermal conductivity of Al<sub>x</sub>Ga<sub>1-x</sub>N (0 ≤ x ≤ 1) epitaxial layers", *Phys. Rev. Materials* **6**, 104602 (2022).

A. Papamichail et al., "Mg-doping and free hole properties of GaN grown by hot-wall MOCVD", *J. Appl. Phys.* **131**, 185704 (2022).

A. Kakanakova et al., "Incorporation of Magnesium into GaN regulated by intentionally large amounts of Hydrogen during growth by MOCVD", *Phys. Status Solidi B* **259**, 2200137 (2022)

M. Schubert et al., "Terahertz electron paramagnetic resonance generalized spectroscopic ellipsometry: The magnetic response of the nitrogen defect in 4H-SiC", *Appl. Phys. Lett.* **120**, 102101 (2022) [link](#)

## *New industrial PhD students!*



**Mado Logotheti**

Volvo Cars & Lund Uni  
Optimization of WBG technologies for fast and efficient power switching



**Pengpeng So**

Volvo Cars & Chalmers  
Design of compact power modules for propulsion and charging applications



**Andreas Divinyi**

Saab & Chalmers  
Thermal aspects of GaN MMICs

## PROJECTS phase 2

Based on the expressed interest and contribution of the industrial partners the following projects during phase 2 of C3NiT are proposed. Project leaders will organize technical discussions in the beginning of 2023 to define the respective project plans, milestones and deliverables.



**D-band**

**D-band HEMTs and MMIC** – Anna Malmros



**Linear E/W-band HEMTs and MMIC** – Mattias Thorsell



**High voltage HEMTs & circuits for power and microwave applications** – Niklas Rorsman



**Vertical devices for power applications**

Muhammad Nawaz and Erik Lind



**Propulsion/Charger/Converter/Switching applications**

Kooros Moabber



**Advanced Epitaxial concepts for cost reduction**

Vanya Darakchieva and Nerijus Armakavicius